



Semiconductor Device Type: (C2A) 128_PQFP14x20x34_MatteTin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	Contained In Sub-Component	% Total Weight	mg/part	ppm	1440.03	(mg) Total	Mold Compound	% of Total Weight	81.75
Fused Silica	60676-86-0	Mold Compound	73.575	1296.024	735.750		Fused Silica	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	4.333	76.321	43.328		Epoxy Resin	Trade Secret	5.30	
Phenol Resin	Trade Secret	Mold Compound	3.679	64.801	36.788		Phenol Resin	Trade Secret	4.50	
Carbon Black	1333-86-4	Mold Compound	0.164	2.880	1.635		Carbon Black	1333-86-4	0.20	
Copper	7440-50-8	Lead Frame	15.715	276.816	157.148		Total			100.00
Nickel	7440-02-0	Lead Frame	0.419	7.382	4.191	290.65	(mg) Total	Lead Frame	% of Total Weight	16.50
Silver	7440-22-4	Lead Frame	0.275	4.851	2.754		Copper	7440-50-8	95.24	
Silicon	7440-21-3	Lead Frame	0.074	1.308	743		Nickel	7440-02-0	2.54	
Magnesium	7439-95-4	Lead Frame	0.017	0.291	165		Silver	7440-22-4	1.67	
Silver	7440-22-4	Die Attach	0.077	1.356	770		Silicon	7440-21-3	0.45	
Acrylic Resin	Trade secret	Die Attach	0.014	0.247	140		Magnesium	7439-95-4	0.10	
Epoxy Resin	Trade secret	Die Attach	0.009	0.159	90		Total			100.00
Silicon	7440-21-3	Chip (Die)	0.750	13.211	7.500	1.76	(mg) Total	Die Attach	% of Total Weight	0.10
Gold	7440-57-5	Wire Bond	0.100	1.762	1.000		Silver	7440-22-4	77.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	0.800	14.092	8.000		Acrylic Resin	Trade secret	14.00	
TOTALS:			100.000	1,761.500	1,000,000		Epoxy Resin	Trade secret	9.00	
1.7615 g Total Mass							Total			100.00
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)						13.21	Total (mg)	Chip (Die)	% of Total Weight	0.75
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.							Doped Silicon	7440-21-3	100.00	
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.							Total			100.00
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/						1.76	(mg) Total	Wire Bond	% of Total Weight	0.10
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.							Gold	7440-57-5	100.00	
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.							Total			100.00
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.						14.09	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	0.80
Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.							Tin	7440-31-5	100.00	
Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table							Total			100.00

1761.50

100.00